



TARGET THICKNESS: 0.062"
NUMBER OF LAYERS: 08

MULTILAYER PCB CONSTRUCTION SHEET

If there are max thickness requirements beyond +/- .10% overall - non-standard construction should be ordered and notes added.

| 8 Layer StackUp (0.062") L08-062-1oz1oz | | Thickness (inches) |
|---|---|-------------------------------|
| Layer 1 | 1 oz foil plated to approximate* thickness 0.0024" | 0.0024 |
| Prepreg | Bonding ply (2x2116) Average Dielectric Constant 4.5 | 0.0084 |
| Layer 2 | 1 oz foil thickness | 0.0014 |
| Core | Laminate Core Dielectric Constant 4.5 (+/- 0.10) | 0.005 |
| Layer 3 | 1 oz foil thickness | 0.0014 |
| Prepreg | Bonding ply (2x2116) Average Dielectric Constant 4.5 | 0.0084 |
| Layer 4 | 1 oz foil thickness | 0.0014 |
| Core | Laminate Core Dielectric Constant 4.5 (+/- 0.10) | 0.005 |
| Layer 5 | 1 oz foil thickness | 0.0014 |
| Prepreg | Bonding ply (2x2116) Average Dielectric Constant 4.5 | 0.0084 |
| Layer 6 | 1 oz foil thickness | 0.0014 |
| Core | Laminate Core Dielectric Constant 4.5 (+/- 0.10) | 0.005 |
| Layer 7 | 1 oz foil thickness | 0.0014 |
| Prepreg | Bonding ply (2x2116) Average Dielectric Constant 4.5 | 0.0084 |
| Layer 8 | 1 oz foil plated to approximate* thickness 0.0024" | 0.0024 |
| "Thickness does not include soldermask or surface finish" | | 0.0618 |

NOTES: